

INTEL ICE LAKE-D XEON PROCESSORS

conga-HPC/sILH



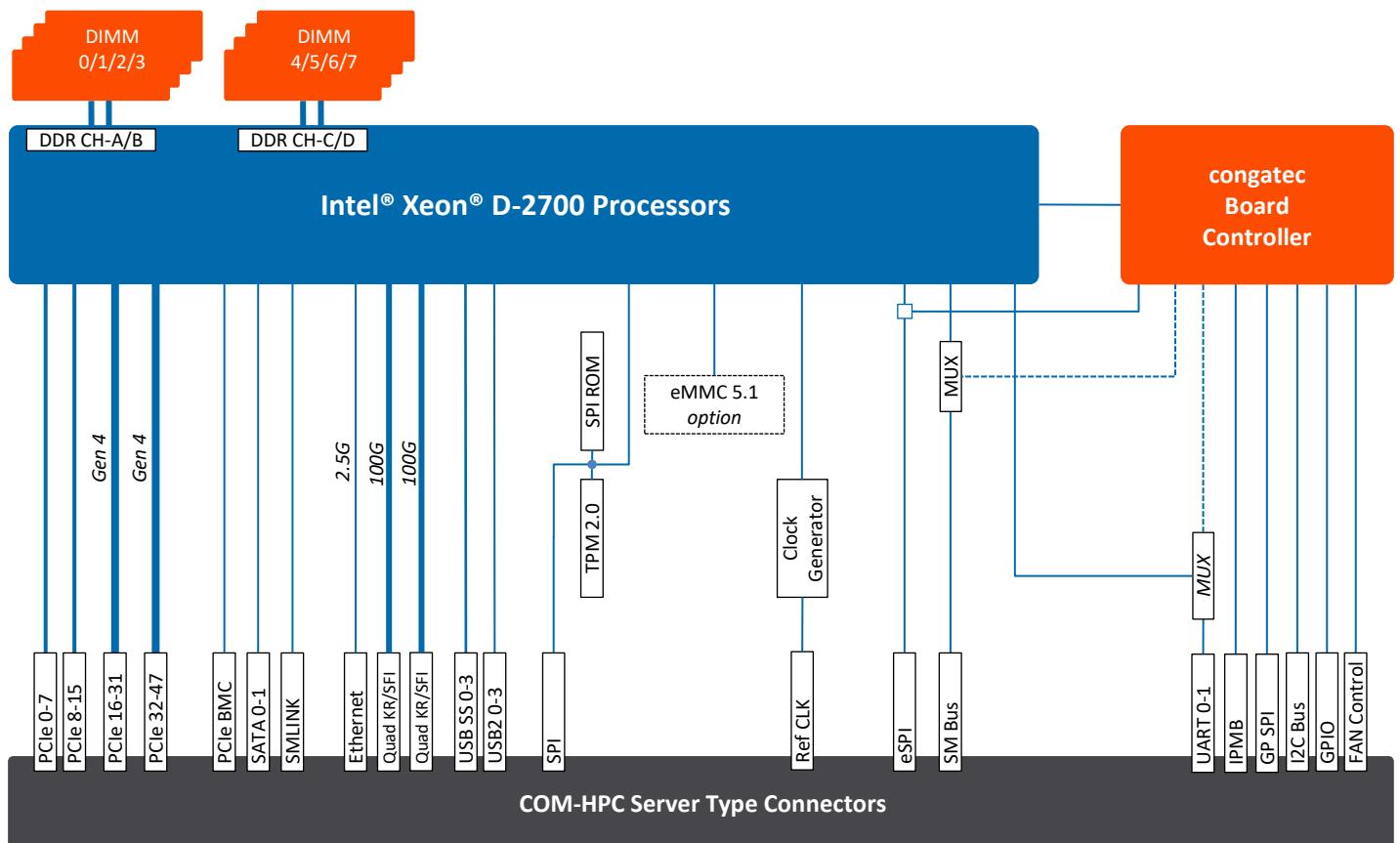
COM+HPC®

- Industrial Use Condition with extended Temperature options
- 48 PCIe Express lanes
- AI Capabilities with Intel® DL boost
- Real Time Capable Platform
- Supporting up to 1 TB DDR4 2933MT/s Memory

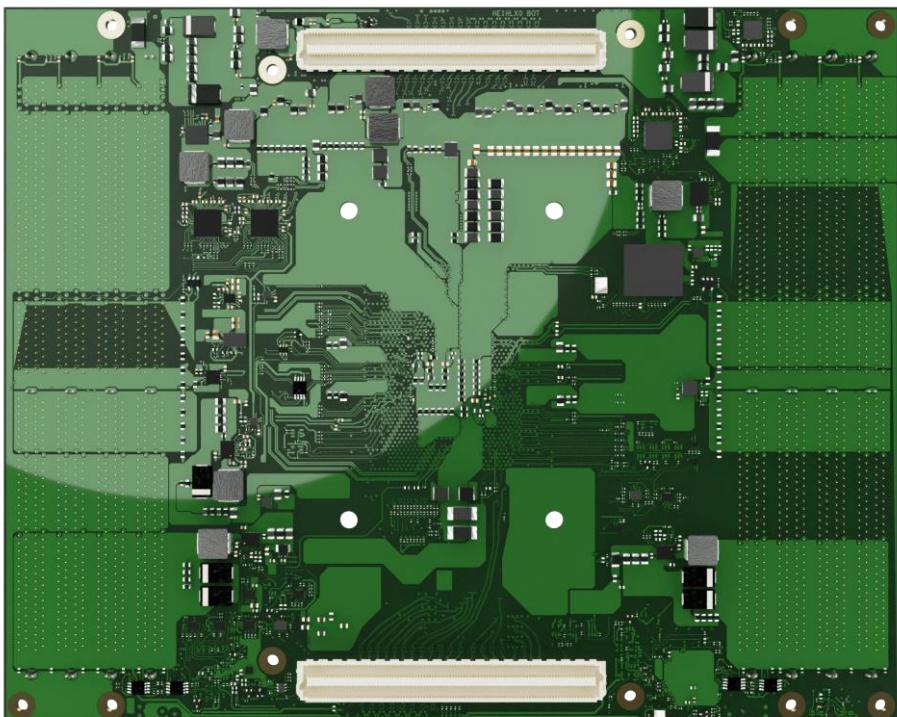
Form Factor											
CPU	Processor	Cores/Threads	Base Frequency/max. Turbo	TDP	Cache	Ethernet Bandwidth					
Xeon® D-2796TE	20C/40T	2.0Ghz/3.1Ghz	118W	30MB	100G	Industrial (Extended Temp)					
Xeon® D-2775TE	16C/32T	2.0Ghz/3.1Ghz	100W	25MB	100G	Industrial (Extended Temp)					
Xeon® D-2752TER	12C/24T	1.8Ghz/2.8Ghz	77W	20MB	50G	Industrial (Extended Temp)					
Xeon® D-2733NT	8C/16T	2.1Ghz/3.2Ghz	80W	15MB	50G	Industrial (Commercial Temp)					
Xeon® D-2712T	4C/8T	1.9Ghz/3.0Ghz	65W	15MB	50G	Industrial (Commercial Temp)					
Chipset	Integrated in SoC										
DRAM	4/8x DIMM sockets for DDR4 memory modules Max. capacity = 1TB										
	Memory Type	DIMM Capacity		Max. DIMM Speed							
	RDIMM	8GB – 64GB		2933 MT/s							
	LRDIMM	64GB – 128GB		2933 MT/s							
	VLP RDIMM	8GB – 64GB		2400 MT/s							
	UDIMM (ECC)	8GB – 32GB		2666 MT/s							
	UDIMM (Non-ECC)	4GB – 32GB		2666 MT/s							
Ethernet	1x 2.5GbE TSN Ethernet 2x 40G / 4x 25G / 8x 10G/2.5G/1G/100M lanes Maximum total bandwidth 100Gb*										
I/O Interfaces	32x PCIe Gen4 16x PCIe Gen3 4x USB 3.0 4x USB 2.0 2x SATA III (6Gb/s) 2x UART 12x GPIO 2x SMBus 2x I2C										
congatec Board controller	Multi-stage Watchdog non-volatile User Data Storage Manufacturing and Board Information Board Statistics I ² C bus (fast mode, 400 kHz, multi-master) Power Loss Control Hardware Health Monitoring POST Code redirection										
Embedded BIOS Feature	AMI Aptio® UEFI firmware 64 Mbyte serial SPI with congatec Embedded BIOS feature OEM Logo OEM CMOS Defaults Flash Update										
Security	Trusted Platform Module (TPM 2.0)										
Power Management	ACPI 5.0 with battery support										
Operating Systems	Microsoft® Windows 10 Microsoft® Windows 10 IoT Enterprise Microsoft® Windows IoT 10 Core Linux Android Yocto RTS Hypervisor										
Temperature Range	Commercial:	Operating Temperature: 0 to +60°C		Storage Temperature: -20 to +80°C*							
	Industrial:	Operating Temperature: -40 to +80°C*		Storage Temperature: -40 to +80°C*							
Humidity	Operating:	10 to 90% r. H. non cond.									
	Storage	5 to 95% r. H. non cond.									
Size	160 x 200 mm ² (optional 160 x 160 mm ²)										

* Depending on CPU

conga-HPC/sILH | Block Diagram



conga-HPC/sILH | Bottom Side View



conga-HPC/sILH | Order Information

Article	PN	Description
conga-HPC/sILH-D2796TE	050900	COM-HPC Size E module based on Intel® Xeon® D-2796TE 20-core processor with 2.0 GHz, 30MB cache and quad channel DDR4 2933 MT/s memory interface (formerly Ice Lake-D HCC). Industrial temperature range.
conga-HPC/sILH-D2775TE	050901	COM-HPC Size E module based on Intel® Xeon® D-2775TE 16-core processor with 2.0 GHz, 25MB cache and quad channel DDR4 2933 MT/s memory interface (formerly Ice Lake-D HCC). Industrial temperature range.
conga-HPC/sILH-D2752TER	050902	COM-HPC Size E module based on Intel® Xeon® D-2752TER 12-core processor with 1.8 GHz, 20MB cache and quad channel DDR4 2666 MT/s memory interface (formerly Ice Lake-D HCC). Industrial temperature range.
conga-HPC/sILH-D2733NT	050910	COM-HPC Size E module based on Intel® Xeon® D-2733NT 8-core processor with 2.1 GHz, 15MB cache and quad channel DDR4 2666 MT/s memory interface (formerly Ice Lake-D HCC). Commercial temperature range.
conga-HPC/sILH-D2712T	050911	COM-HPC Size E module based on Intel® Xeon® D-2712T 4-core processor with 1.9 GHz, 15MB cache and quad channel DDR4 2666 MT/s memory interface (formerly Ice Lake-D HCC). Commercial temperature range.
conga-HPC/sILH-CSA-HP-B	050950	Standard active cooling solution for COM-HPC Server modules conga-HPC/sILH with integrated heat pipes, 32.9mm overall cooling height and integrated 12V fan. Through hole mounting with bore hole standoffs Ø2.7mm.
conga-HPC/sILH-CSA-HP-T	050951	Standard active cooling solution for COM-HPC Server modules conga-HPC/sILH with integrated heat pipes, 32.9mm overall cooling height and integrated 12V fan. Threaded mounting with threaded standoffs M2.5.
conga-HPC/sILH-HSP-HP-B	050952	Standard heatspreader for COM-HPC Server modules conga-HPC/sILH with integrated heat pipes and 11mm overall cooling height. Through hole mounting with bore hole standoffs Ø2.7mm.
conga-HPC/sILH-HSP-HP-T	050953	Standard heatspreader for COM-HPC Server modules conga-HPC/sILH with integrated heat pipes and 11mm overall cooling height. Threaded mounting with threaded standoffs M2.5.
conga-HPC/sILH-HPA-B	050954	Heat pipe Adapter for COM-HPC Server modules conga-HPC/sILH. Suitable for standard 8 mm heat pipes to optimize heat distribution. Through hole mounting with bore hole standoffs Ø2.7mm.
conga-HPC/sILH-HPA-T	050955	Heat pipe Adapter for COM-HPC Server modules conga-HPC/sILH. Suitable for standard 8 mm heat pipes to optimize heat distribution. Threaded mounting with threaded standoffs M2.5.
conga-HPC/EVAL-Server	065500	conga-HPC/EVAL-Server